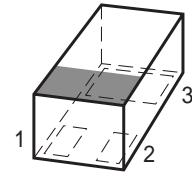


NPN Silicon RF Transistor*

- Low voltage/ Low current operation
- For low noise amplifiers
- For Oscillators up to 3.5 GHz and Pout > 10 dBm
- Low noise figure: 1.0 dB at 1.8 GHz
- Pb-free (RoHS compliant) package¹⁾
- Qualified according AEC Q101

* Short term description



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BFR360L3	FB	1 = B	2 = E	3 = C	TSLP-3-1

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	6	V
Collector-emitter voltage	V_{CES}	15	
Collector-base voltage	V_{CBO}	15	
Emitter-base voltage	V_{EBO}	2	
Collector current	I_C	35	mA
Base current	I_B	4	
Total power dissipation ²⁾ $T_S \leq 104^\circ\text{C}$	P_{tot}	210	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Ambient temperature	T_A	-65 ... 150	
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ³⁾	R_{thJS}	≤ 220	K/W

¹Pb-containing package may be available upon special request

² T_S is measured on the collector lead at the soldering point to the pcb

³For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Collector-emitter breakdown voltage $I_C = 1 \text{ mA}, I_B = 0$	$V_{(\text{BR})\text{CEO}}$	6	9	-	V
Collector-emitter cutoff current $V_{CE} = 15 \text{ V}, V_{BE} = 0$	I_{CES}	-	-	10	μA
Collector-base cutoff current $V_{CB} = 5 \text{ V}, I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 1 \text{ V}, I_C = 0$	I_{EBO}	-	-	1	μA
DC current gain- $I_C = 15 \text{ mA}, V_{CE} = 3 \text{ V}$, pulse measured	h_{FE}	90	120	160	-

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency $I_C = 15 \text{ mA}, V_{CE} = 3 \text{ V}, f = 1 \text{ GHz}$	f_T	11	14	-	GHz
Collector-base capacitance $V_{CB} = 5 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0 \text{ , emitter grounded}$	C_{cb}	-	0.26	0.4	pF
Collector emitter capacitance $V_{CE} = 5 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0 \text{ , base grounded}$	C_{ce}	-	0.15	-	
Emitter-base capacitance $V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{CB} = 0 \text{ , collector grounded}$	C_{eb}	-	0.42	-	
Noise figure $I_C = 3 \text{ mA}, V_{CE} = 3 \text{ V}, Z_S = Z_{\text{Sopt}}, f = 1.8 \text{ GHz}$ $I_C = 3 \text{ mA}, V_{CE} = 3 \text{ V}, Z_S = Z_{\text{Sopt}}, f = 3 \text{ GHz}$	F_{min}	-	1	-	dB
-		-	1.3	-	
Power gain, maximum available ¹⁾ $I_C = 15 \text{ mA}, V_{CE} = 3 \text{ V}, Z_S = Z_{\text{Sopt}}, Z_L = Z_{\text{Lopt}} \text{ , } f = 1.8 \text{ GHz}$ $I_C = 15 \text{ mA}, V_{CE} = 3 \text{ V}, Z_S = Z_{\text{Sopt}}, Z_L = Z_{\text{Lopt}} \text{ , } f = 3 \text{ GHz}$	G_{ma}	-	16	-	
-		-	11.5	-	
Transducer gain $I_C = 15 \text{ mA}, V_{CE} = 3 \text{ V}, Z_S = Z_L = 50\Omega \text{ , } f = 1.8 \text{ GHz}$ $f = 3 \text{ GHz}$	$ S_{21e} ^2$	-	13.5	-	dB
-		-	9	-	
Third order intercept point at output ²⁾ $V_{CE} = 3 \text{ V}, I_C = 15 \text{ mA}, Z_S=Z_L=50 \Omega, f = 1.8 \text{ GHz}$	IP_3	-	24	-	dBm
1dB Compression point at output $I_C = 15 \text{ mA}, V_{CE} = 3 \text{ V}, Z_S=Z_L=50 \Omega, f = 1.8 \text{ GHz}$	$P_{-1\text{dB}}$	-	9	-	

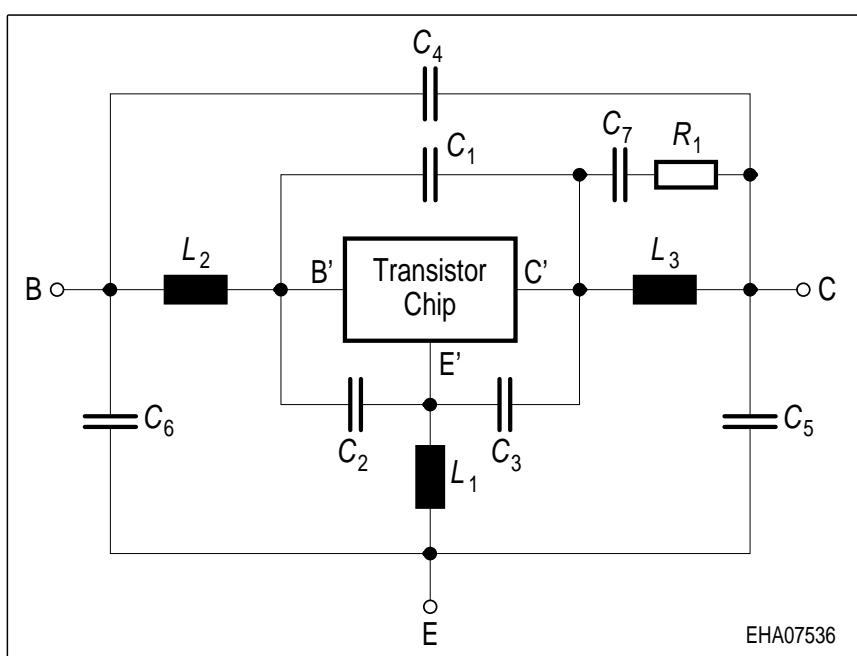
¹⁾ $G_{\text{ma}} = |S_{21e}| / S_{12e} | (k - (k^2 - 1)^{1/2})$
²⁾IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):
Transistor Chip Data:

IS =	0.0689	fA	BF =	147	-	NF =	1	-
VAF =	20	V	IKF =	77.28	mA	ISE =	150	fA
NE =	2.4	-	BR =	6	-	NR =	1	-
VAR =	60	V	IKR =	0.3	A	ISC =	20	fA
NC =	1.4	-	RB =	0.1	Ω	IRB =	74	μ A
RBM =	7.31	Ω	RE =	78.2	$m\Omega$	RC =	0.35	Ω
CJE =	400	fF	VJE =	1.3	V	MJE =	0.5	-
TF =	9.219	ps	XTF =	0.115	-	VTF =	0.198	V
ITF =	1.336	mA	PTF =	0	deg	CJC =	473	fF
VJC =	0.864	V	MJC =	0.486	-	XCJC =	0.129	-
TR =	1.92	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	XTB =	0	-	EG =	1.11	eV
XTI =	0	-	FC =	0.954		NK =	0.5	K
AF =	1	-	KF =	1E-14				

All parameters are ready to use, no scaling is necessary.

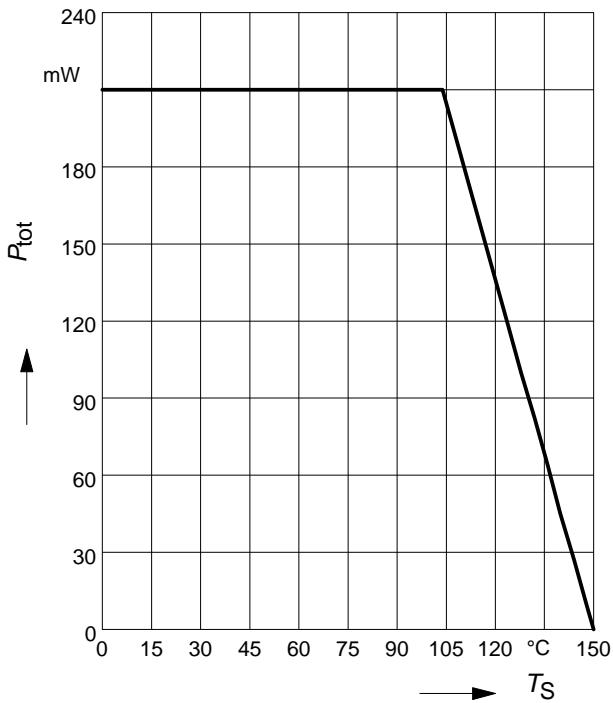
Package Equivalent Circuit:


L_1 =	0.575	nH
L_2 =	0.575	nH
L_3 =	0.275	nH
C_1 =	33	fF
C_2 =	28	fF
C_3 =	131	fF
C_4 =	8	fF
C_5 =	8	fF
C_6 =	24	fF
C_7 =	300	fF
R_1 =	204	Ω

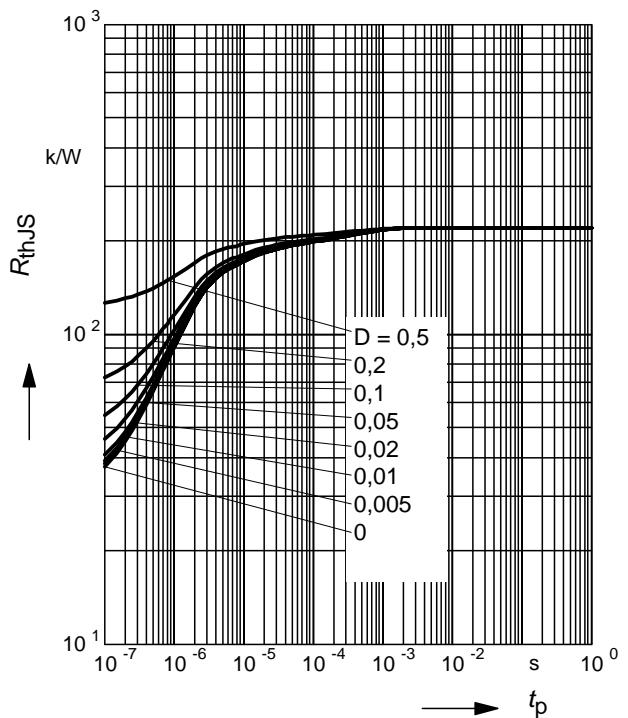
Valid up to 6GHz

For examples and ready to use parameters
please contact your local Infineon Technologies
distributor or sales office to obtain a Infineon
Technologies CD-ROM or see Internet:
<http://www.infineon.com>

Total power dissipation $P_{\text{tot}} = f(T_S)$

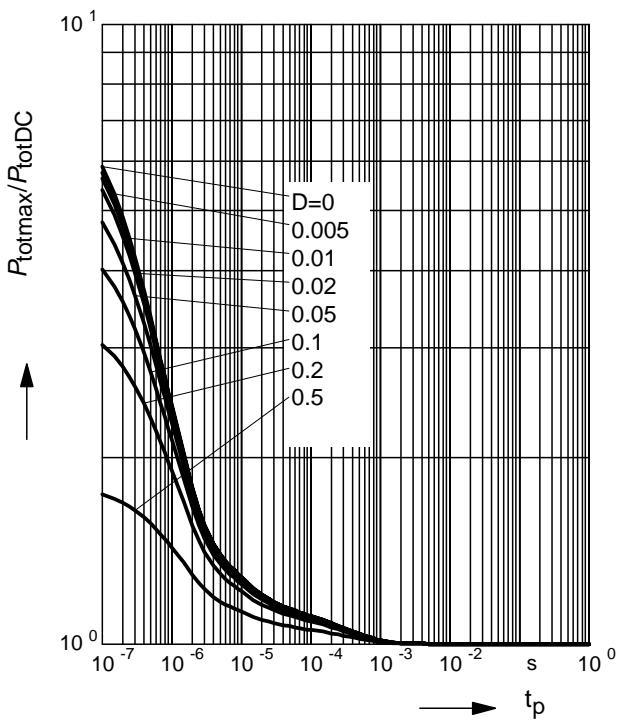


Permissible Pulse Load $R_{\text{thJS}} = f(t_p)$



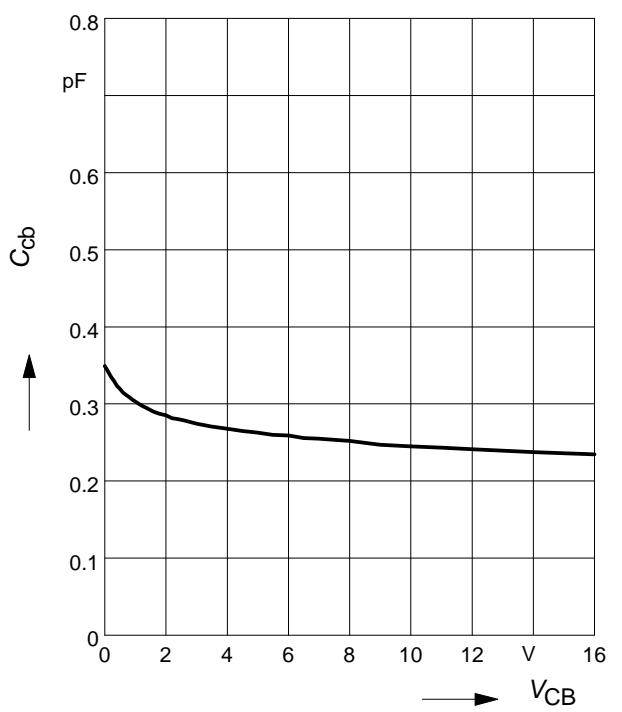
Permissible Pulse Load

$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$



Collector-base capacitance $C_{\text{cb}} = f(V_{\text{CB}})$

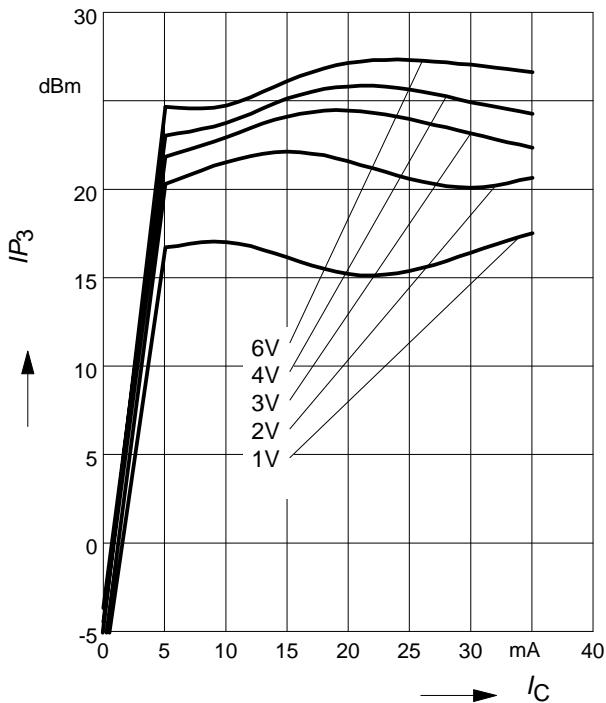
$$f = 1\text{MHz}$$



Third order Intercept Point $IP_3=f(I_C)$

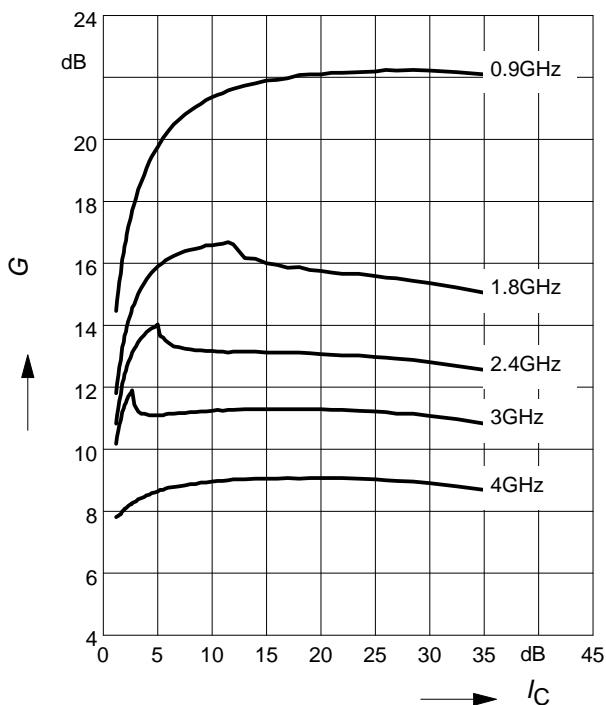
(Output, $Z_S=Z_L=50\Omega$)

V_{CE} = parameter, $f = 1.8$ GHz


Power gain $G_{ma}, G_{ms} = f(I_C)$

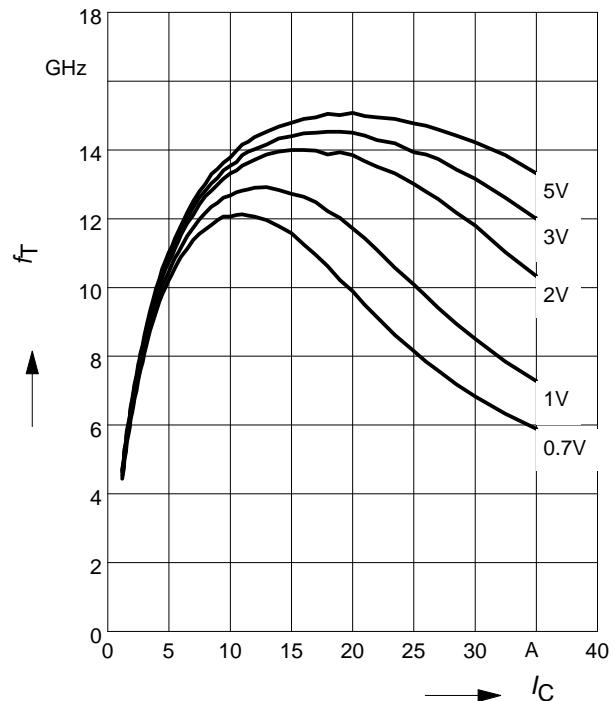
$V_{CE} = 3$ V

f = parameter in GHz


Transition frequency $f_T = f(I_C)$

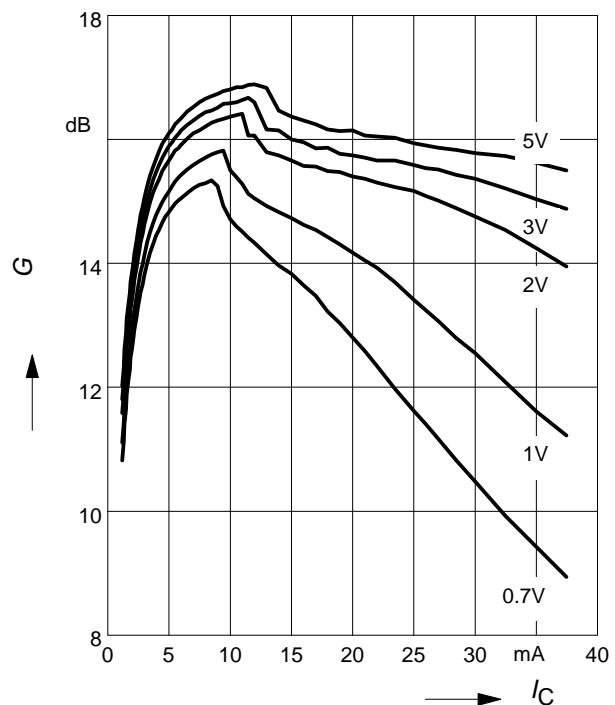
$f = 1$ GHz

V_{CE} = parameter


Power gain $G_{ma}, G_{ms} = f(I_C)$

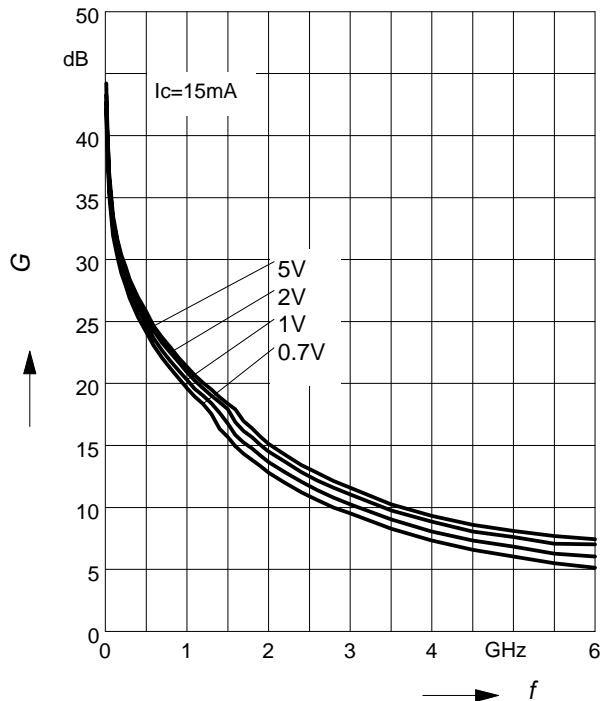
$f = 1.8$ GHz

V_{CE} = parameter



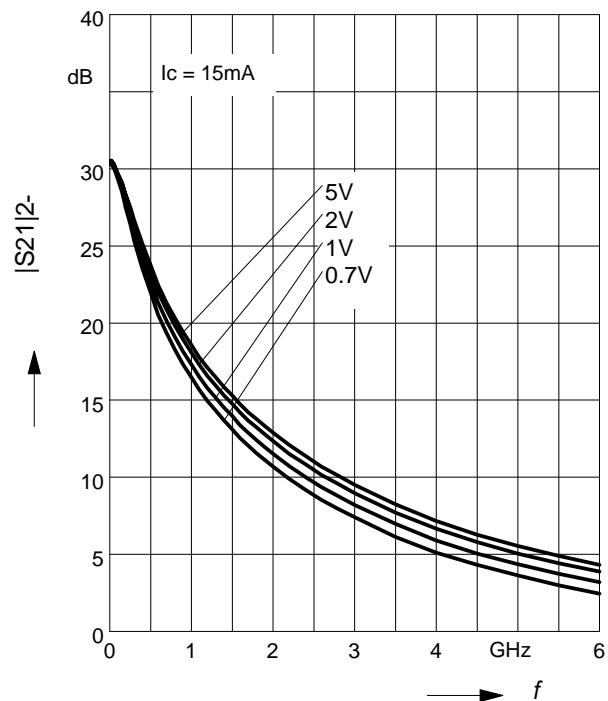
Power Gain G_{ma} , $G_{ms} = f(f)$

V_{CE} = parameter



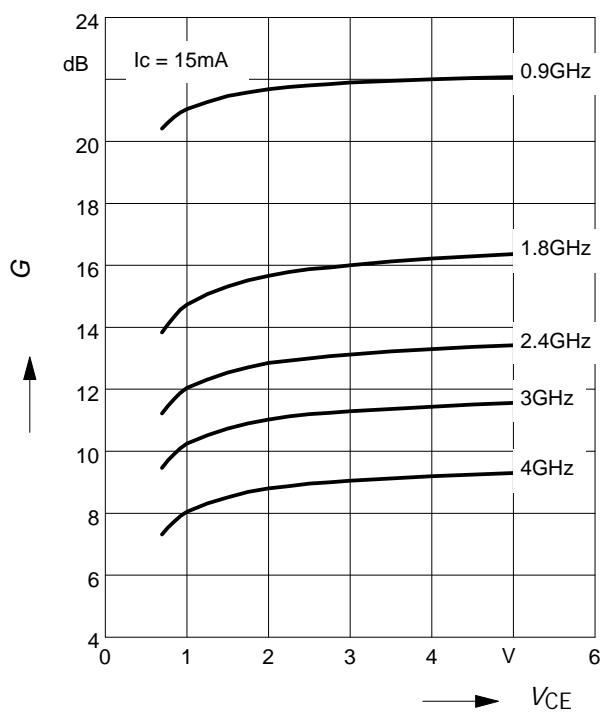
Power Gain $|S_{21}|^2 = f(f)$

V_{CE} = parameter

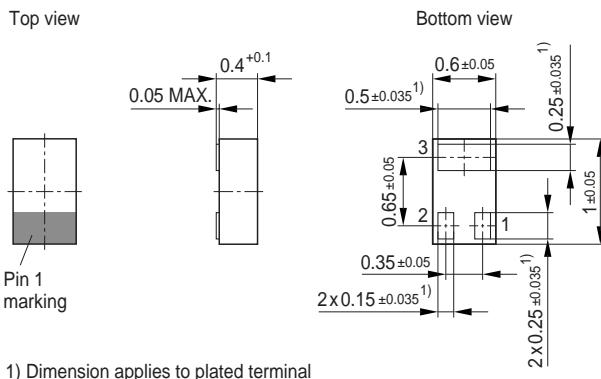


Power Gain G_{ma} , $G_{ms} = f(V_{CE})$:

f = parameter

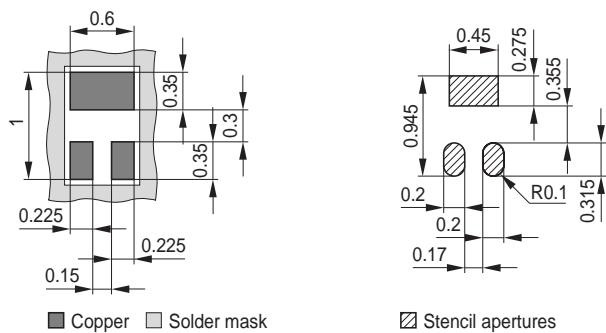


Package Outline

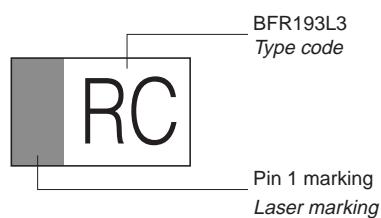


Foot Print

For board assembly information please refer to Infineon website "Packages"

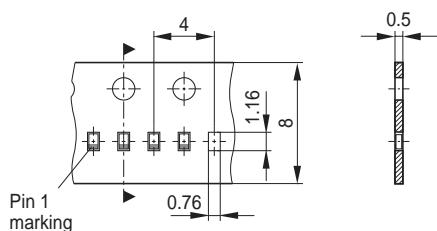


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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- Техническая поддержка проекта;
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Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.